

**Product Change Notification - KSRA-05ATCO683**


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**Date:**

05 Jul 2019

**Product Category:**

Linear Regulators; Others

**Affected CPNs:**

**Notification subject:**

CCB 3454 and 3454.001 Final Notice: Qualification of GTBF as a new assembly site for selected products of 0.8um XFAB, 0.8um AMS and 0.6um AMI, 130K and 133K wafer technologies available in 3L and 5L DDPAK packages with MSL 3 classification.

**Notification text:**
**PCN Status:**

Final notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

**NOTE:** For your convenience Microchip includes identical files in two formats (.pdf and)

**Description of Change:**

Qualification of GTBF as a new assembly site for selected products of 0.8um XFAB, 0.8um AMS and 0.6um AMI, 130K and 133K wafer technologies available in 3L and 5L DDPAK packages.

**Pre Change:**

Assembled at CARSEM using 84-1 LMISR4 die attach, CEL-9240HF10 molding compound and HCL-12S material with MSL 1 classification

**Post Change:**

Assembled at GTBF using CRM-1800 die attach, EME-G600 molding compound and LY80 material with MSL 3 classification

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	Carsem (M) SDN BHD CARM)	Great Team Backend Foundry (Dong Guan) Ltd. GTBF)
<b>Wire material</b>	Au wire	Au wire
<b>Die attach material</b>	84-1 LMISR4	CRM-1800
<b>Molding compound material</b>	CEL-9240HF10	EME-G600
<b>Lead frame material</b>	HCL-12S	LY80
<b>MSL Classification</b>	MSL 1	MSL 3

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve on-time delivery performance by qualifying GTBF as a new assembly site. no longer have manufacturing support for the selected products.

**Change Implementation Status:**

In Progress



**Estimated First Ship Date:**

August 05, 2019 (date code: 1932)

NOTE: Please be advised that after the estimated first ship may receive pre and post change parts.

**Time Table Summary:**

	August 2018						July 2019				August 2019				
Workweek	31	32	33	34	35		27	28	29	30	31	32	33	34	35
Initial PCN Issue Date		X													
Report Availability							X								
Final PCN Issue Date							X								
Estimated Implementation Date												X			

**Method to Identify Change:**

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report

**Revision History:**

**August 10, 2018:** Issued initial notification.

**March 11, 2019:** initial notification Updated the plan to change the MSL level classification and added hot temperature 125&deg;C in

**July 05, 2019:** Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided to be on August 05, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_KSRA-05ATCO683\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

MCP1790-3002E/EB  
MCP1790-3302E/EB  
MCP1790-5002E/EB  
MCP1790T-3002E/EB  
MCP1790T-3302E/EB  
MCP1790T-3302E/EBVAO  
MCP1790T-5002E/EB  
MCP1790T-5002E/EBVAO  
MCP1791-3002E/ET  
MCP1791-3302E/ET  
MCP1791-5002E/ET  
MCP1791T-3002E/ET  
MCP1791T-3302E/ET  
MCP1791T-5002E/ET  
MCP1825-0802E/ET  
MCP1825-1202E/ET  
MCP1825-1802E/ET  
MCP1825-2502E/ET  
MCP1825-3002E/ET  
MCP1825-3302E/ET  
MCP1825-5002E/ET  
MCP1825-ADJE/ET  
MCP1825S-0802E/EB  
MCP1825S-1202E/EB  
MCP1825S-1802E/EB  
MCP1825S-2502E/EB  
MCP1825S-3002E/EB  
MCP1825S-3302E/EB  
MCP1825S-5002E/EB  
MCP1825ST-0802E/EB  
MCP1825ST-1202E/EB  
MCP1825ST-1802E/EB  
MCP1825ST-2502E/EB  
MCP1825ST-3002E/EB  
MCP1825ST-3302E/EB  
MCP1825ST-3302E/EBVAO  
MCP1825ST-5002E/EB  
MCP1825T-0802E/ET  
MCP1825T-1202E/ET  
MCP1825T-1802E/ET  
MCP1825T-2502E/ET  
MCP1825T-3002E/ET  
MCP1825T-3302E/ET  
MCP1825T-5002E/ET  
MCP1825T-ADJE/ET  
MCP1825T-ADJE/ETVAO

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MCP1826-0802E/ET

MCP1826-1202E/ET

MCP1826-1802E/ET

MCP1826-2502E/ET

MCP1826-3002E/ET

MCP1826-3302E/ET

MCP1826-5002E/ET

MCP1826-ADJE/ET

MCP1826S-0802E/EB

MCP1826S-1202E/EB

MCP1826S-1802E/EB

MCP1826S-2502E/EB

MCP1826S-3002E/EB

MCP1826S-3302E/EB

MCP1826S-5002E/EB

MCP1826ST-0802E/EB

MCP1826ST-1202E/EB

MCP1826ST-1802E/EB

MCP1826ST-2502E/EB

MCP1826ST-3002E/EB

MCP1826ST-3302E/EB

MCP1826ST-5002E/EB

MCP1826T-0802E/ET

MCP1826T-1202E/ET

MCP1826T-1802E/ET

MCP1826T-2502E/ET

MCP1826T-3002E/ET

MCP1826T-3302E/ET

MCP1826T-5002E/ET

MCP1826T-ADJE/ET

MCP1827-0802E/ET

MCP1827-1002E/ET

MCP1827-1202E/ET

MCP1827-1802E/ET

MCP1827-2502E/ET

MCP1827-3002E/ET

MCP1827-3302E/ET

MCP1827-5002E/ET

MCP1827-ADJE/ET

MCP1827S-0802E/EB

MCP1827S-1002E/EB

MCP1827S-1202E/EB

MCP1827S-1802E/EB

MCP1827S-2502E/EB

MCP1827S-3002E/EB

MCP1827S-3302E/EB

MCP1827S-5002E/EB

MCP1827ST-0802E/EB

MCP1827ST-1002E/EB

MCP1827ST-1202E/EB

MCP1827ST-1802E/EB

MCP1827ST-2502E/EB

MCP1827ST-3002E/EB

MCP1827ST-3302E/EB

MCP1827ST-5002E/EB

MCP1827T-0802E/ET

MCP1827T-1002E/ET

MCP1827T-1202E/ET

MCP1827T-1802E/ET

MCP1827T-2502E/ET

MCP1827T-3002E/ET

MCP1827T-3302E/ET

MCP1827T-5002E/ET

MCP1827T-ADJE/ET

TC1262-2.5VEB

TC1262-2.5VEBTR

TC1262-2.8VEB

TC1262-2.8VEBTR

TC1262-3.0VEB

TC1262-3.0VEBTR

TC1262-3.3VEB

TC1262-3.3VEBTR

TC1262-5.0VEB

TC1262-5.0VEBTR

TC1263-2.5VET

TC1263-2.5VETTR

TC1263-2.8VET

TC1263-2.8VETTR

TC1263-3.0VET

TC1263-3.0VETTR

TC1263-3.3VET

TC1263-3.3VETTR

TC1263-5.0VET

TC1263-5.0VETTR

TC1264-1.8VEB

TC1264-1.8VEBTR

TC1264-2.5VEB

TC1264-2.5VEBTR

TC1264-3.0VEB

TC1264-3.0VEBTR

TC1264-3.3VEB

TC1264-3.3VEBTR

TC1265-1.8VET

TC1265-1.8VETTR

TC1265-2.5VET

TC1265-2.5VETTR

TC1265-3.0VET

TC1265-3.0VETTR

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TC1265-3.3VE1

TC1265-3.3VETTR

TC2117-1.8VEB

TC2117-1.8VEBTR

TC2117-2.5VEB

TC2117-2.5VEBTR

TC2117-3.0VEB

TC2117-3.0VEBTR

TC2117-3.3VEB

TC2117-3.3VEBTR